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Hayes

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Kazuhiko TAKADA

Serial No.: 09/528,296

Group Art Unit: 2811

Filed: March 17, 2000

Examiner: Ori NAVAV

For: SEMICONDUCTOR DEVICE HAVING A GUARD RING

**PRELIMINARY AMENDMENT AND
REQUEST FOR INTERVIEW**

Commissioner for Patents
Washington, D.C. 20231

Date: February 19, 2002

Sir:

Please amend the above-identified application as follows:

IN THE CLAIMS:

Amend the claims 1 and 6 as follows:

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1. (Twice Amended) A semiconductor device, comprising:
- a substrate; and
 - a multilayer interconnection structure formed on said substrate,
- said multilayer interconnection structure including: at least first and second interlayer insulation films provided on said substrate; and a guard ring pattern embedded in each of said first and second interlayer insulation films, said guard ring pattern extending along a periphery of said substrate, said multilayer interconnection structure being planarized by using a CMP process,

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